



Item	Quantity	Part Reference	Value	Package	Description	Manufacturer	Manufacturer Part Number	Comments
1	3	C1 C17 C18	10uF	0805	CAP, CERAMIC, 10uF, 10V, X7R, 10%, 0805	Murata	GRM21BR71A106KE51L	
2	23	C2 C4 C5 C6 C7 C8 C9 C10 C11 C12 C13 C15 C19 C20 C22 C24 C25 C26 C28 C29 C31 C32 C33	100nF	0201	CAP, CERAMIC, 100nF, 10V, X5R, 20%, 0201	Panasonic	ECJZEB1A104M	
3	2	C3 C27	2200nF	0603	CAP, CERAMIC, 2200nF, 10V, X5R, 20%, 0603	Panasonic	ECJ1VB1A225M	
4	3	C14 C21 C23	1uF	0402	CAP, CERAMIC, 1uF, 6.3V, X7R, 10%, 0402	Kemet	C0402C105K9RACTU	
5	2	C16 C30	10nF	0201	CAP, CERAMIC, 10nF, 10V, X5R, 10%, 0201	Panasonic	ECJZEB1A103K	
6	1	J1	SOCKET-28-2X14-J(CLE)		CONN, SOCKET, VERTICAL, 2x14, 28 PIN, .0315 PITCH, SMT	Samtec	CLE-114-01-G-DV	
7	1	MP1	CMT821		CAMERA LENS MOUNT, BARREL THREAD, M12x0.5, W/ 2 MTG HOLES	SUNEX	CMT821	
8	5	R1 R2 R3 R9 R13	10K	0201	RESISTOR, THICK FILM CHIP, SMD, 10K, 0.05W, 5%, 0201	Panasonic	ERJ1GEJ103C	
9	2	R4 R5	1	0402	RESISTOR, THICK FILM CHIP, SMD, 1 OHM, 0.063W, 1%, 0402	Vishay Dale	CRCW04021R00FKED	
10	1	R6	10	0402	RESISTOR, THICK FILM CHIP, SMD, 10 OHM, 0.063W, 5%, 0402	Panasonic	ERJ2GEJ100X	
11	1	R7	5.1	0402	RESISTOR, THICK FILM CHIP, SMD, 5.1 OHM, 0.1W, 5%, 0402	Panasonic	ERJ2GEJ5R1X	
12	1	R8	0	0201	RESISTOR, THICK FILM CHIP, SMD, 0 OHM JUMPER, 0.05W, 5%, 0201	Panasonic	ERJ1GE0R00C	
13	1	R10	33	0201	RESISTOR, THICK FILM CHIP, SMD, 33 OHM, 0.05W, 5%, 0201	Panasonic	ERJ1GEJ330C	
14	2	R11 R12	1.5K	0603	RESISTOR, THICK FILM CHIP, SMD, 1.5K, 0.1W, 5%, 0603	Panasonic	ERJ3GEYJ152V	

15	1	U1	MI1000-C24A-iBGA64	iBGA64	IC, SENSOR, ACTIVE-PIXEL DIGITAL IMAGE, CMOS, C24A DEMO HDBD, MI1000, iBGA64	Aptina Imaging	MI1000-iBGA64-DEMO	
16	1	U2	AP0101	VBGA81	IC, IMAGE COPROCESSOR, AP0101, DEMO HDBD, VBGA81	Aptina Imaging	AP0101	
17	1	U3	M95M01-DFCS6P	WLCSP8	IC,EEPROM,SERIAL PERIPHERAL INTERFACE BUS,1.7V-5.5V,WLCSP8	STMicroelectronics	M95M01-DFCS6P	

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